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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jung-Chih HU et al.

Confirmation No.: 5769

Serial No.: 10/070,000

Examiner: Edna Wong

Filed: November 27, 2002

Group Art Unit: 1753

Title: ELECTROPLATING SOLUTION FOR COPPER ELECTROPLATING

SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please substitute the attached thirty-two (32) formal drawings for the informal drawings filed in the above-identified application.

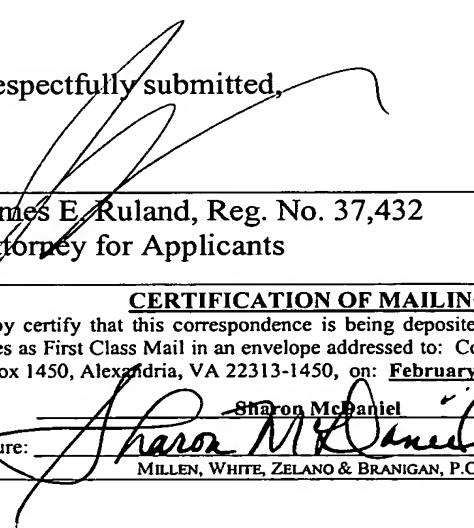
No fee is believed to be due in association with this filing, however, the Commissioner is hereby authorized to charge fees under 37 C.F.R. §§ 1.16 and 1.17 which may be required to facilitate this filing, or credit any overpayment to Deposit Account No. 13-3402.

Respectfully submitted,

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CERTIFICATION OF MAILING	
I hereby certify that this correspondence is being deposited with the U.S. Postal Services as First Class Mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on: <u>February 9, 2004</u>	
Name:	Sharon McDaniel
Signature:	
MILLEN, WHITE, ZELANO & BRANIGAN, P.C.	

Attorney Docket No.: MERCK-2395

Date: February 9, 2004